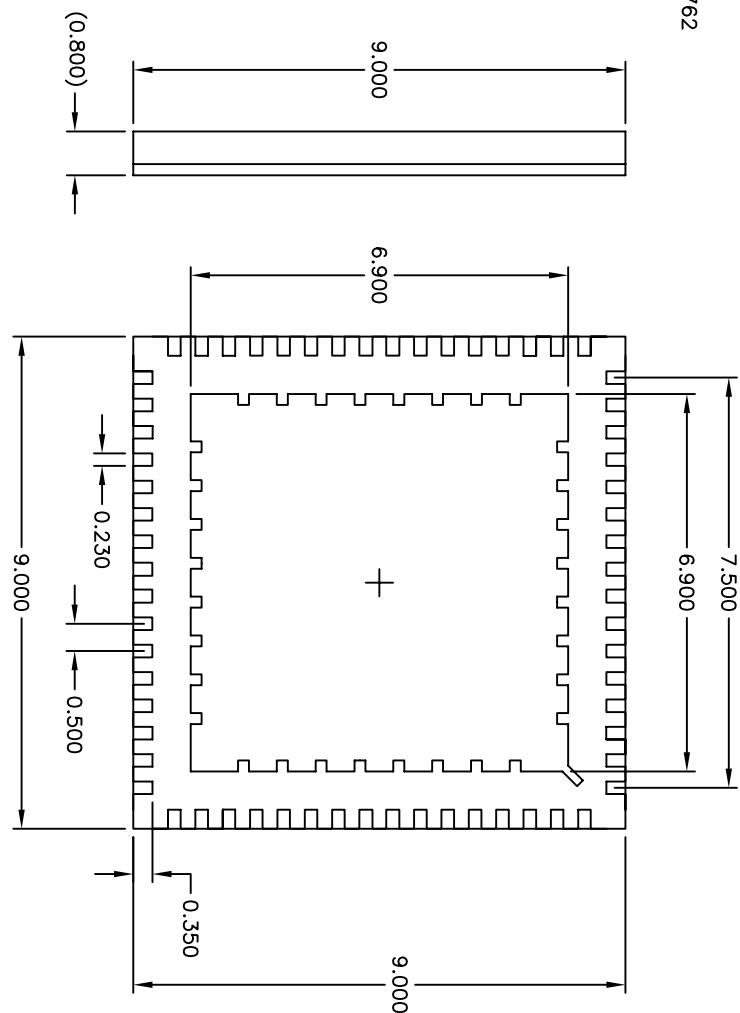
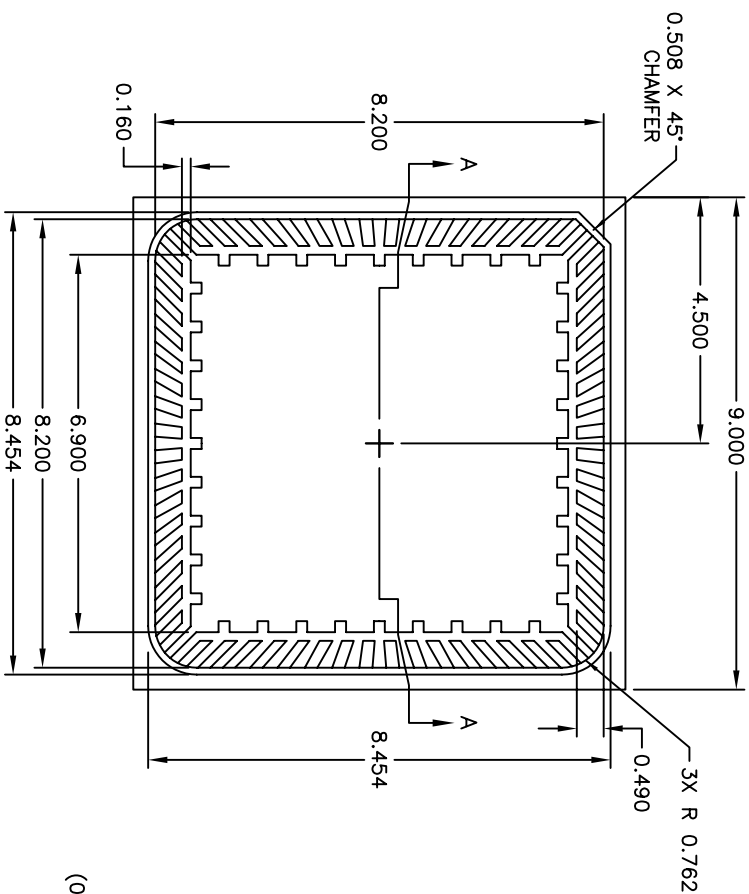


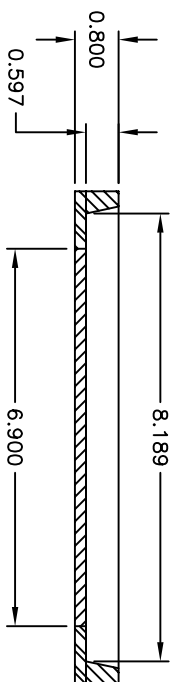
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REVISIONS			
ECN NO.	DATE	DESCRIPTION	APPROVED
10638	04/01/06	PRODUCTION RELEASE	D.BENANDO



SECTION A-A



- NOTES:
1. BODY: PLASTIC, SEMICONDUCTOR GRADE.
 2. LEAD FRAME: COPPER, 194 FH.
 3. LEAD FINISH: FULL GOLD PLATE.
 4. FRAME THICKNESS: 0.2030 ± 0.0076
 5. DIE PAD: 6.900 X 6.900
 6. JEDEC OUTLINE: MO-220.



UNLESS OTHERWISE SPECIFIED
DIMENSIONS ARE IN MILLIMETERS
TOLERANCES ARE:

X.XX ± 0.15 X.XXX ± ---
X.XXX ± 0.100 ANGLES: ± 1°

DO NOT SCALE DRAWING

DRAWN BY W. GRIFFITHS
DATE 04/01/06
P. FLASKERUD
DATE 04/01/06

CUSTOMER
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SIZE PART NO. 64 Lead 9mm x 9mm
A MLP9X9-64-OP-01
SCALE NONE FILE MLP9X9-64-OP-01-R1.DWG SHEET 1 OF 1

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